ISOCOM[®]LTD

IECQ-CECC

QC 88000-C003

COMPONENT

SPECIFICATION

ISSUE 4

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Component Specification For Ceramic Hermetically Sealed High Gain Optocouplers



Up-to-date lists and bibliographical references of IEQC-CECC publications may be downloaded from www.iecq.org

Further copies of this document may be obtained from:

IEC

International Electrotechnical Commission Commission Electrotechnique Internationale

Box 131, rue de Varembé, CH 1211 Geneva 20, Switzerland

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FOREWORD

The IECQ Quality Assessment System for Electronic Components (IECQ) is composed of those member countries of the International Electrotechnical Commission (IEC) who wish to take part in a harmonized system for electronic components of assessed quality. IECQ is also known in some European member countries as IECQ-CECC.

The object of the System is to facilitate international trade by the harmonization of the specifications and quality assessment procedures for electronic components, and by the grant of an internationally recognised Mark, or Certificate of Conformity. The components produced or services provided under the system are thereby acceptable in all member countries without further testing.

This Component Specification is based upon the requirements of IEC Publication QC 001002-2, and has been prepared by:

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AMENDMENT RECORD

Issue 1 – Changed Pages 4, 9 & 10 – Amendments 25/06/10 Issue 2 – Changed Pages 3, 4 & 5 – Amendments 05/07/10 Issue 3 – Changed Pages 3, 4, 5 & 6 – RoHS Compliant, Added CSM160/161/162-2 & Amendments 13/07/10

REQUIREMENTS

The requirements for IECQ-CECC Component Specifications as detailed in QC 001002-2 Amendment 1 clause 5.4 are satisfied by the following data sheet.

It should note that IECQ-CECC are not responsible for manufacturers declarations made in data sheets which fall outside the limits of approved detailed in IECQ-CECC certificates.

This Component Specification is intended for use with applicable IECQ-CECC Assessment Specifications. Eg: QC 88000-A0001

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Ceramic Hermetically Sealed High Gain Optocouplers

- 6N140A
- CD750
- CD5731
- CH370
- CS700

Features

- Release to IECQ-CECC
- Hermetically Sealed
- High Density Packaging
- 1500V DC withstand Test Voltage
- Low Input Requirements: 0.5mA
- High Current Transfer Ratio: 1000% Typical
- RoHS Compliant

Description

- **CS5700**
- CSM141/A
- **CSM160/161/162-2**
- **CSM160/161/162-4**
- **CSM1700**

Applications

- Military, high reliability system
- Medical instruments
- Mos, Cmos Applications
- Logic Interfacing
- Data Transmission
- Transportation

Each channel contains a light emitting diode which is optically coupled to an integrated high gain photon detector. The high gain output stage features an open collector output providing both lower saturation voltage and higher signalling speed than a conventional Photo-Darlington optocoupler. The supply voltage can be operated as low as 2.0V without adversely affecting the parametric performance. The High Current Transfer Ratio of the optocouplers makes them ideal for low input current, min 0.5mA, applications.

The radiation immunity of the optocouplers compared to conventional photo transistor optocouplers is due to the shallow depth and small junctions offered by the IC process.

The optocoupler family is also available in various package styles including 6, 8 and 16 pin DIP through hole, 16 pin surface mount DIP flat pack and a 6 Pin leadless ceramic chip carrier. The devices can be purchased with lead bend and plating options.

ISOCOM optocouplers are offered on the basis of similarity of emitter and detector therefore the performance characterization is identical, subject to the limitations of the packages. The wafer die similarities apply to the optocouplers for high reliability screening and radiation testing.

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Selection Guide Package Styles and Configuration Options

Package	5 pin Hybrid	6 Pad LCC	8 pin DIP	8 pin DIP	16 pin DIP	16 pin Flat Pack
Lead Style						
Channels	1	1	1	2	4	2/4
Common Channel Wiring						
Isocom Part Numbers and C	Options					
		CSM141A	CS5700	CD750		CSM160/161/
Commercial	CH370	CSM1700	CS700	CD5731	6N140A	162
		CSM141A/L2	CS5700/L2	CD750/L2		CSM160/161/
Defense Level	CH370/L2	CSM1700/L2	CS700/L2	CD5731/L2	6N140A/L2	162/L2
		CSM141A/L2S	CS5700/L2S	CD750/L2S		CSM160/161/
Space Level	CH370/L2S	CSM1700/L2S	CS700/L2S	CD5731/L2S	6N140A/L2S	162/L2S
Standard Gold Plate Finish		Gold Plate	Gold Plate	Gold Plate	Gold Plate	Gold Plate
Solder Dipped			Option 20	Option 20	Option 20	
Butt Cut/Gold Plate			Option 10	Option 10	Option 10	
Gull Wing/Soldered			Option 30	Option 30	Option 30	
Crew Cut/Gold Plate			Option 60	Option 60	Option 60	

Functional Diagrams

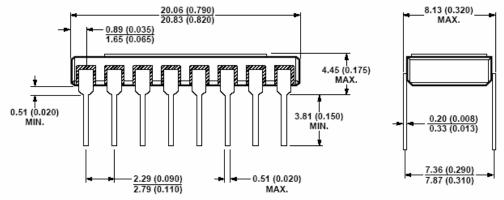
CH370	CSM141A	CS5700 CS700	CD750 CD5731	6N140A	CSM160/161 /162-2
5 pin Hybrid	6 Pad LCC	8 pin DIP	8 pin DIP	16 pin DIP	16 pin Flat Pack
1 Channel	1 Channel	1 Channel	2 Channel	4 Channel	2 Channel
				16 15 14 13 12 11 10 9 <u>※ </u>	16 15 14 13 12 11 10 9 → ÂÂ ³ <u>r2h</u> rKh 1 2 3 4 5 6 7 8
	CSM1700				CSM160/161 /162-4
	6 Pad LCC 1 Channel				16 pin Flat Pack 4 Channel
					16 15 14 13 12 11 10 9 <u>※ </u>

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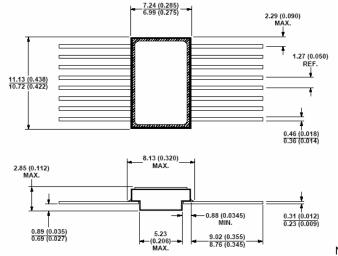


Outline Drawings

16 pin DIP, 4 Channel

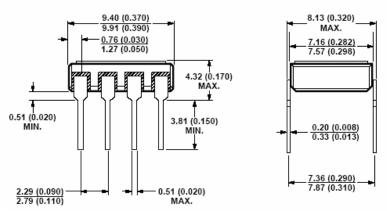


16 pin Flat Pack, 2 and 4 Channel



NOTE: DIMENSIONS IN MILLIMETERS

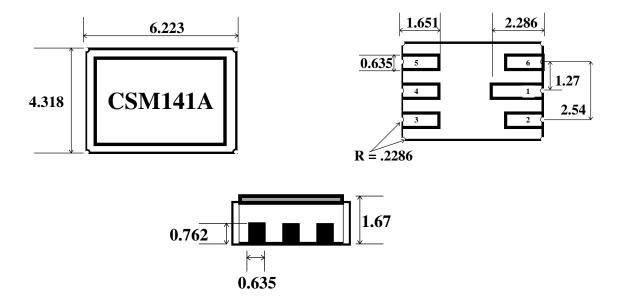
8 pin DIP 1 and 2 Channel



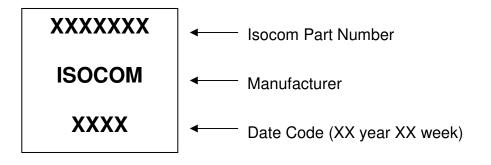
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6 Terminal LCC Surface Mount, 1 Channel



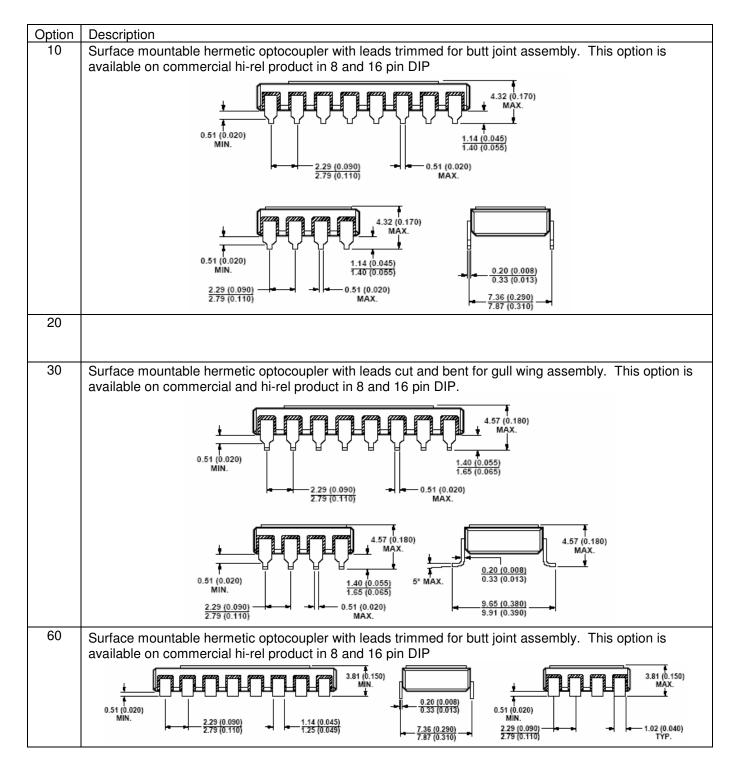
Device Marking



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Hermetic Optocoupler Options



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Absolute Maximum Ratings

Storage Temperature	-65℃ to +150℃
Operating Temperature	-55℃ to +125℃
Lead Soldering Temperature	260C for 10S, 1.6mm below seating plane where appropriate

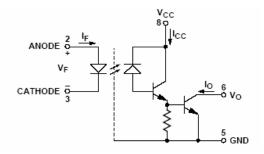
Input Diode

Peak Forward Current	20mA	\leq 1 mS duration, 500pps
Average Forward Current	10mA	(See note 3)
Reverse Voltage	5V	
Power Dissipation	35mW	

Output Detector

Supply Voltage	-0.5 to 20V	V _{CC} (See note 1)
Current	40mA	lo
Collector Power Dissipation	50mW	(See note 2)
Voltage	-0.5 to 20V	V _O (See note 1)

Single Channel Schematic



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Parameter	Symbol	Test Conditions	Device	Min	Туре	Max	Units
High Level Output	I _{OH}	$I_F = 2\mu A$,		-	0.001	250	μΑ
Current (See notes 4 & 6)	I _{OHX}	$V_{\rm O} = V_{\rm CC} = 5.5 V$					
Lower Level Output	V _{OL}	$I_F = 0.5mA$, $I_{OL} = 1.5mA$, $V_{CC} = 4.5V$		-	0.1	0.4	V
Voltage (See note 4)		$I_F = 5mA$, $I_{OL} = 10mA$, $V_{CC} = 4.5V$		-	0.15	0.4	
High Level Supply	I _{CCH}	$V_{CC} = 18V, I_{F1} = I_{F2} = I_{F3} = I_{F4} = 0$		-	0.1	40	μΑ
Current		$V_{CC} = 5.5, I_{F1} = I_{F2} = I_{F3} = I_{F4} = 0$	CSM160/1			60	
Low Level Supply Current	I _{CCL}	$V_{CC} = 18V, I_{F1} = I_{F2} = I_{F3} = I_{F4} = 1.6mA$		-	1.4	4	mA
(See note 4)		$V_{CC} = 5.5V, I_{F1} = I_{F2} = I_{F3} = I_{F4} = 4mA$	CSM160/1			8	
Input-Output Insulation Leakage Current (See notes 7 & 13)	I _{I-O}	RH = 45%, T _A = 25°C, t = 5S V _{IO} = 1500Vdc		-	-	1.0	μA
Input Forward Voltage	V _F	I _F = 1.6mA, T _A = 25 ℃		-	1.45	1.9	V
(See note 4)	·	$I_F = 4.0 \text{mA}$	CSM160/1	-			
Input Reverse Breakdown Voltage (See note 4)	B _{VR}	I _R = 10μA, T _A = 25 ℃		5	-	-	V
Propagation Delay Time to Logic High Output	t _{PLH}	$R_L = 4.7K\Omega$, $V_{CC} = 5V$, $I_F = 0.5mA$, $T_A = 25^{\circ}C$	6N140 CS5700 CSM6730 CH370 CD750 CSM1700	-	8	60	μS
			CSM160/1			100	
(See note 4)		$R_{L} = 680\Omega, V_{CC} = 5V, I_{F} = 5mA,$	6N140	-	8	20	
		$T_A = 25^{\circ}C$	CS5700 CSM6730			30	-
			CH390 CD750 CSM1700			60	-
Propagation Delay Time to Logic Low Output	tPHL	RL = 4.7KΩ, VCC = 5V, IF = 0.5mA, TA = 25 ℃	CH370 CD750 CSM1700	-	35	100	μS
			CSM160 CSM161 CS5700 CSM6730			100	-
(See note 4)		RL = 680Ω, VCC = 5V, IF = 5mA, TA = 25 °C	CH390 CD750 CSM1700	-	3	12	
			CS5700 CSM6730			10	
			CSM160/1			5	
Current Transfer Ratio	CTR	IF = 0.5mA, VO = 0.4V, VCC = 4.5V		300	700	-	%
(See notes 4 & 5)		IF = 1.6mA, VO = 0.4V, VCC = 4.5V		200	1000	-	
		IF = 5mA, VO = 0.4V, VCC = 4.5V		200	600	-	1

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Electrical Characteristics (Continued)

Common Mode Transient Immunity at Logical High Output Level (See notes 4, 10 & 12)	CM _H	$\label{eq:V_CC} \begin{array}{l} V_{CC}=5V,\ T_A=25^\circ\!\!C,\ V_{CM}=50V\ p\text{-}p\\ \hline R_L=1.5K\Omega,\ I_F=0Ma\\ \hline R_L=2.2K\Omega,\ I_F=0MA \end{array}$	CH370 CS700 CSM1700 CSM6730	500	1000	-	V/µS
Common Mode Transient Immunity at Logical Low Output Level (See notes 4, 10 & 12)	CML	$\begin{split} V_{CC} &= 5V, \ T_A = 25 \ ^{\circ}\!\!^{\circ}\!\!^{\circ}\!\!^{\circ}, \ V_{CM} = 50V \ p\text{-}p \\ \hline R_L &= 1.5 K\Omega, \ I_F = 1.6 mA \\ \hline R_L &= 2.2 K\Omega, \ I_F = 1.6 mA \end{split}$	CH370 CS700 CSM1700 CSM6730	500	-1000	-	V/µS

Typical Characteristics

Parameter	Symbol	Test Conditions	Notes	Min	Туре	Max	Units
Resistance	R _{IO}	V ₁₀ = 500Vdc	4 & 8	-	10 ¹²	-	Ω
Capacitance	C _{IO}	f = 1MHz	4 & 8	-	1.5	-	рF
Input Capacitance	C _{IN}	$f = 1MHz, V_F = 0$	4	-	60	-	рF
Temperature Coefficient of Forward Voltage	$\frac{\Delta_{\rm VF}}{\Delta_{\rm TA}}$	I _F = 1.6mA	1	-	-1.8	-	mV/° C
Input-Input Insulation Leakage Current	IIII	45% Relative Humidity $V_{II} = 500Vdc, t = 5S$	9	-	0.6	-	nA
Resistance	R _{I-I}	$V_{II} = 500 V dc$	9	-	10 ¹²	-	Ω
Capacitance	C ₁₋₁	f = 1MHz	9	-	1	-	рF

Notes:

1. The ground pin should be the most negative voltage at the detector side. Keeping V_{CC} as low as possible, but greater than 2.0V, will provide lowest total I_{OH} over temperature.

2. Output power is collector output plus one fourth of total supply power. Derate at 1.66mW/°C above 110 °C.

3. Derate I_F at 0.33mA/℃ above 110℃.

4. Each channel.

5. Current Transfer Ratio is defined as the ratio of output collector current, I_0 , to the forward LED input current, I_F , times 100%.

6. I_{OHX} is the leakage current resulting from channel to channel optical crosstalk. $I_F = 2\mu A$ for channel under test. For all other channels, $I_F = 10mA$.

7. Input pins are shorted together, and output pins are shorted together.

8. Measured between the LED anode and cathode shorted together and pins at output shorted together.

9. Measured between adjacent input pairs shorted together.

10. CM_H is the maximum tolerable common mode transient to assure that the output will remain in a high logic state (i.e., $V_O > 2.0V$).

11. CM_L is the maximum tolerable common mode transient to assure that the output will remain in the logic low state (i.e., $V_O < 0.8V$).

12. In applications where dV/dt may exceed 50,000V/ μ S (such as a static discharge), a series resistor, R_{CC}, should be included to protect the detector IC's from destructively high surge currents. The recommended value is

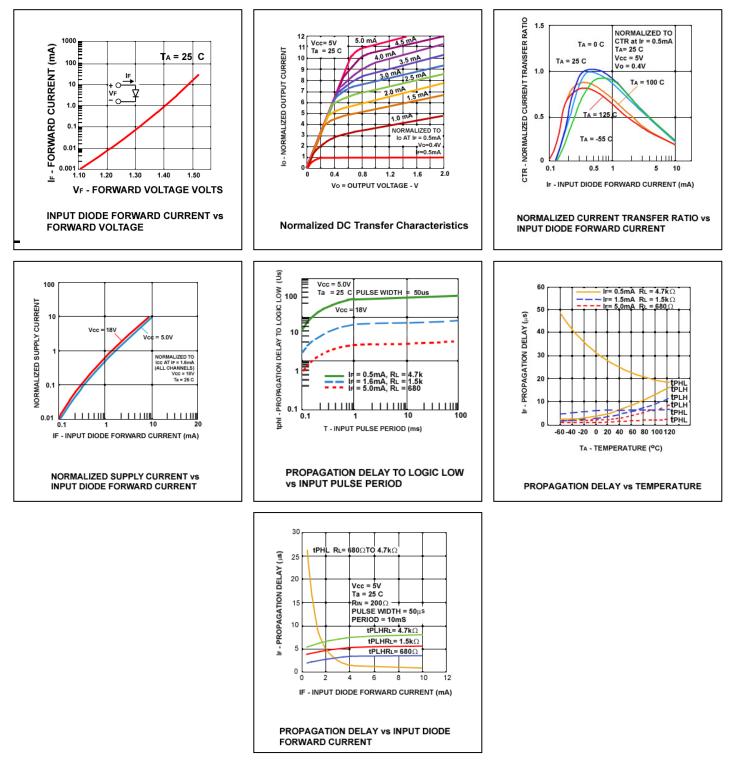
$$R_{CC} = \frac{1V}{0.6I_{F}(mA)} k\Omega$$

13. This is a momentary withstand test, not an operating condition.

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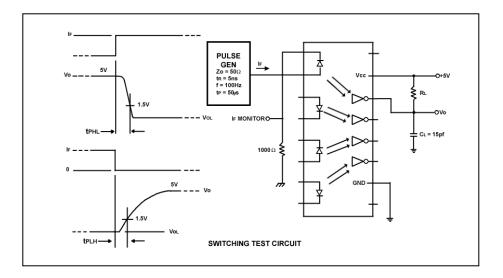


Electrical Characteristics



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